

MEMS ENCLOSURE

ABSTRACT OF THE DISCLOSURE

A low-cost, high-performance, reliable micromirror package (300) that replaces the ceramic substrate in
5 conventional packages with a printed circuit board substrate (30) and a molded plastic case (33), and the cover glass with a window (36), preferably an optically clear plastic window. The printed circuit board substrate (30) allows for either external bond pads or
10 flex cable connection of the micromirror package to the projector's motherboard. These packages support flexible snap-in, screw-in, ultrasonic plastic welding, or adhesive welding processes to overcome the high cost seam welding process of many conventional packages.